

RTA of MOVPE-grown Mg-doped $\text{In}_x\text{Ga}_{1-x}\text{N}$ ($x \sim 0.3$) for Mg activationUniv. of Fukui¹, JST-CREST², Osaka City Univ.³Md. Tanvir Hasan^{1,2}, A. Mihara^{1,2}, N. Shigekawa³, A. Yamamoto^{1,2}, M. Kuzuhara¹

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Introduction: Achieving highly conductive p-type GaN and related alloys is a key issue in the nitride semiconductor device fabrication. Nakamura et al reported that the annealing temperature (T_{act}) should be higher than 700°C for achieving low resistivity of Mg-doped GaN films [1]. For InGaN, there is a possibility that the annealing at high T_{act} can bring about phase separation [2] of grown films. Recently, we have reported that the phase separation in $\text{In}_x\text{Ga}_{1-x}\text{N}$ ($x \sim 0.3$) is suppressed by reducing growth temperature to around 570°C [3]. In this paper, we report the rapid thermal annealing (RTA) of Mg-doped $\text{In}_x\text{Ga}_{1-x}\text{N}$ ($x \sim 0.36$) grown by MOVPE. P-type samples are successfully obtained by using RTA at around 850°C.

Experiments: The growth of InGaN alloys was conducted using a MOVPE system. TEG, TMI, and NH_3 were used for Ga, In, and N sources, respectively. Cp_2Mg was used for Mg source. Growth temperature and pressure were fixed at 570°C and 150 Torr, respectively. Two types of substrates, AlN/Si and $\alpha\text{-Al}_2\text{O}_3$, were employed. The growth rate of InGaN was about 0.5 $\mu\text{m/h}$ with In content of 0.36. Finally, samples were annealed in N_2 using RTA. For comparison, the furnace annealing was also employed.

Results and discussion: Figure 1 shows the cross-sectional SEM images for as-grown and furnace-annealed (at 650°C for 20 min) samples. The annealed sample has a porous region in the film, showing the decomposition (phase separation) of the InGaN film [3]. Figure 2 shows the cross-sectional SEM images for as-grown and RTA (at 850°C for 10 sec) samples. One can see that no porous region exists in the annealed sample. Thus, it is confirmed

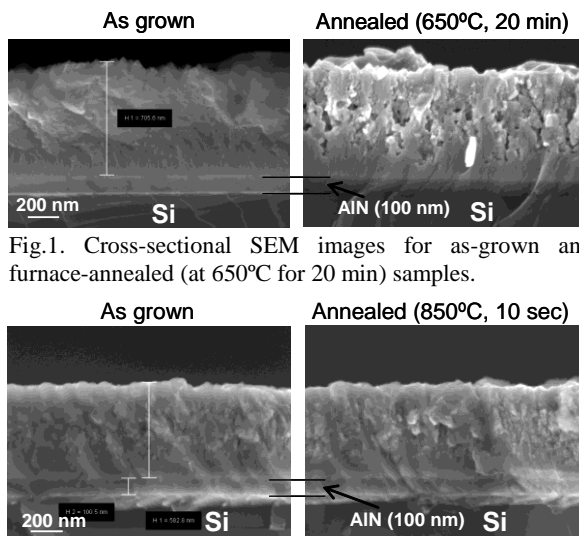


Fig.1. Cross-sectional SEM images for as-grown and furnace-annealed (at 650°C for 20 min) samples.

Fig.2. Cross-sectional SEM images for as-grown and RTA (at 850°C for 10 sec) samples.

that the decomposition of InGaN can be suppressed by reducing annealing time, even if T_{act} is much higher than growth temperature.

Figure 3 shows the T_{act} dependence of carrier concentration and Hall mobility for RTA $\text{In}_x\text{Ga}_{1-x}\text{N}$ ($x \sim 0.36$) grown at 570°C. As shown in this figure, the carrier concentration is increased and Hall mobility is decreased with increasing T_{act} . The p-type conduction was confirmed by Hall and thermo-voltaic measurements for samples annealed at 850°C. For samples annealed at 700-800°C, p-type conduction was confirmed only by thermo-voltaic measurements. For the rest of samples, conduction type could not be identified. These results indicate that Mg-acceptor activation annealing should be done above 700°C.

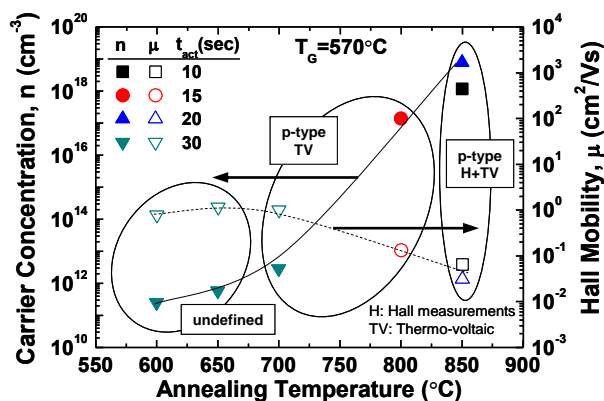


Fig.3. Carrier concentration and mobility of RTA InGaN samples grown at 570 °C.

Conclusion: This paper reports the rapid thermal annealing (RTA) of Mg-doped $\text{In}_x\text{Ga}_{1-x}\text{N}$ ($x \sim 0.36$) grown by MOVPE. P-type samples are successfully obtained by using RTA at around 850°C.

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